

OptoTEC™ OTX Series Thermoelectric Cooler

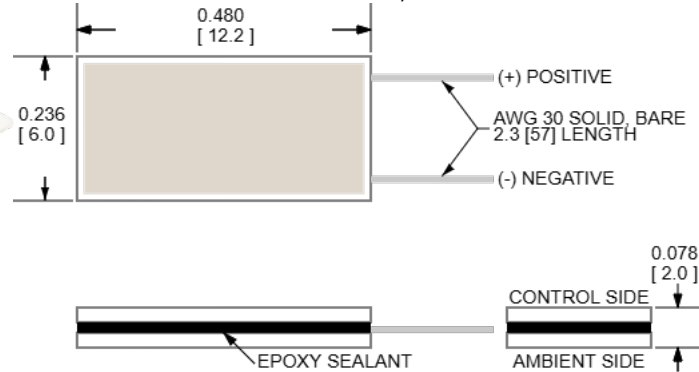
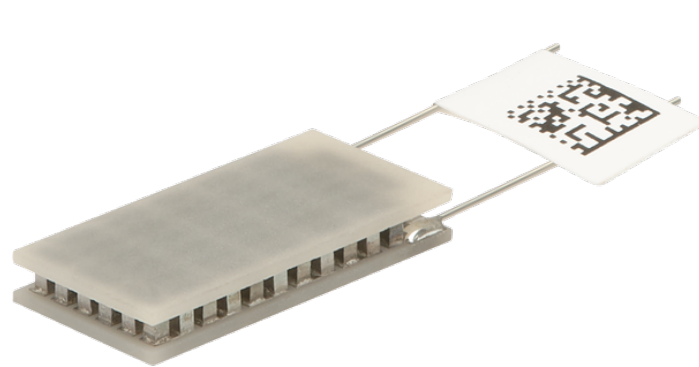
The OTX19-35-F1N-0612-21-EP-W2.25 is a high-performance, miniature thermoelectric cooler. The OTX19-35-F1N-0612-21-EP-W2.25 is primarily used in applications to stabilize the temperature of sensitive optical components in the telecom and photonics industries. It has a maximum Q_c of 4.7 Watts when $\Delta T = 0$ and a maximum ΔT of 72.9 °C at $Q_c = 0$.

Features

- Miniature footprint
- Precise temperature control
- Reliable solid-state operation
- No sound or vibration
- RoHS-compliant

Applications

- Laser Diodes
- Optical Transceivers
- Lidar Sensors
- Infrared Range (IR) Sensors
- CMOS Sensors
- Autonomous Systems
- Machine Vision
- Security Cameras



CERAMIC MATERIAL: AlN

SOLDER CONSTRUCTION: 232°C, SbSn

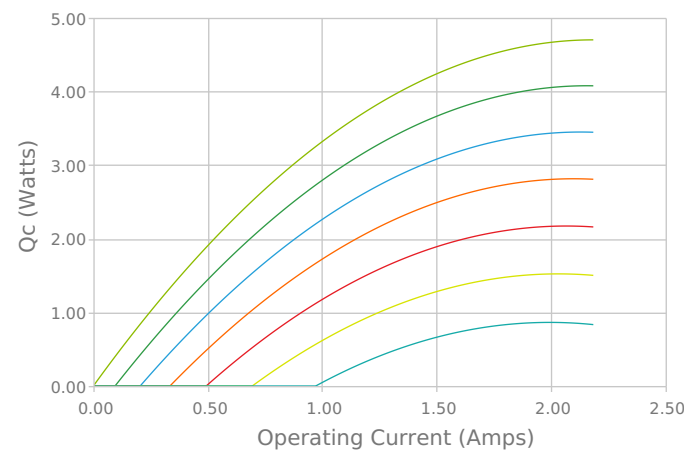
INCHES [MM]

Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

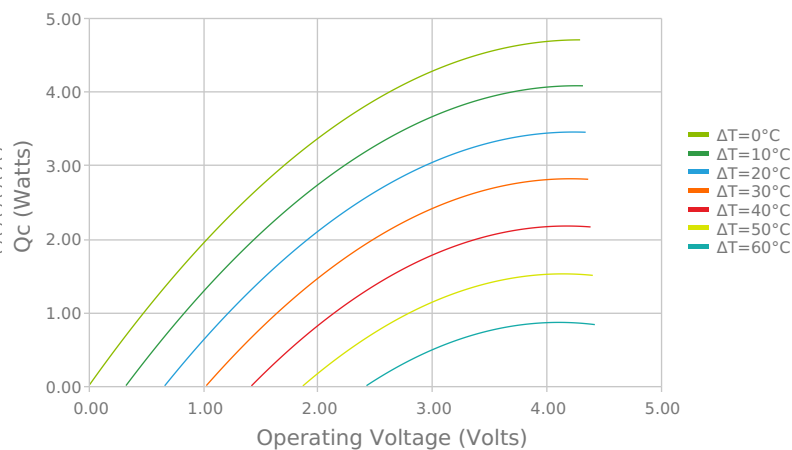
Electrical and Thermal Performance

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the AMBIENT side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

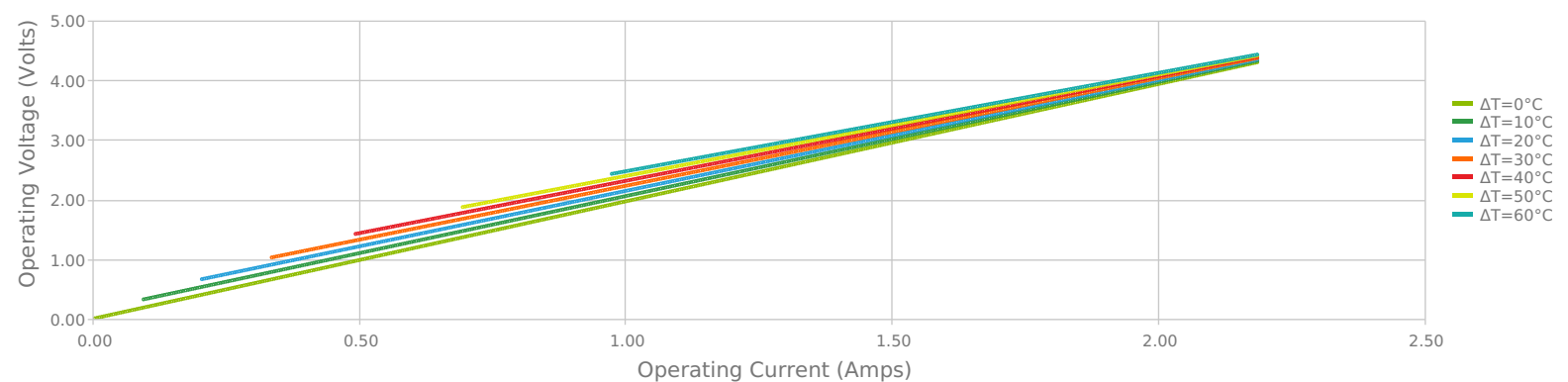
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



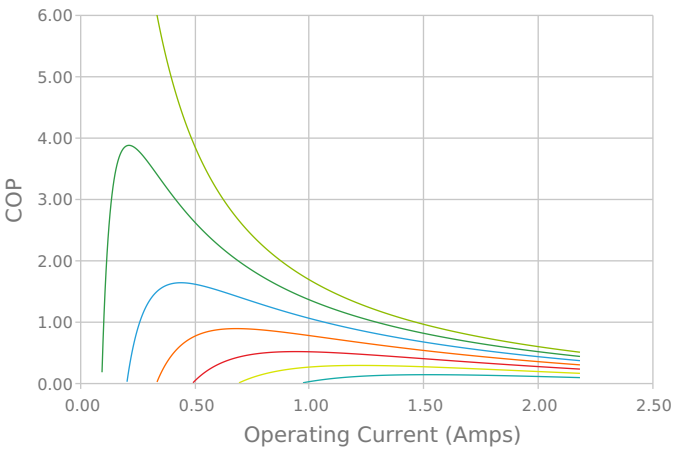
Heat Pumped at Cold Side
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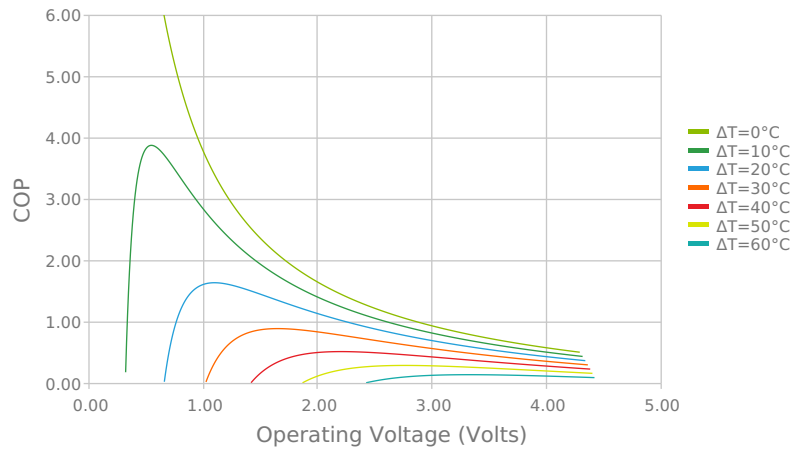
Current vs Voltage (I vs V)
 $T_{hot} = 27\text{ °C}$



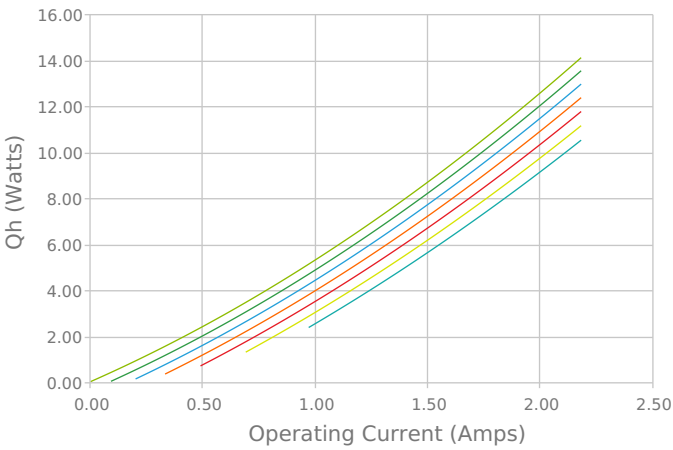
Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



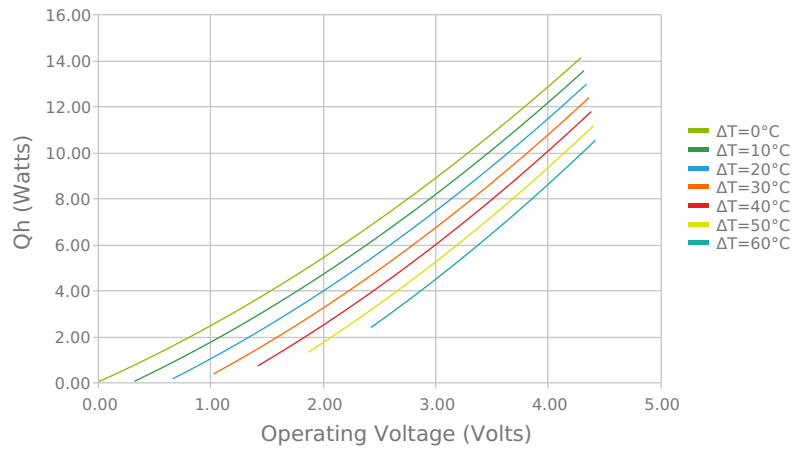
Coefficient of Performance (COP = Q_c/P_{in})
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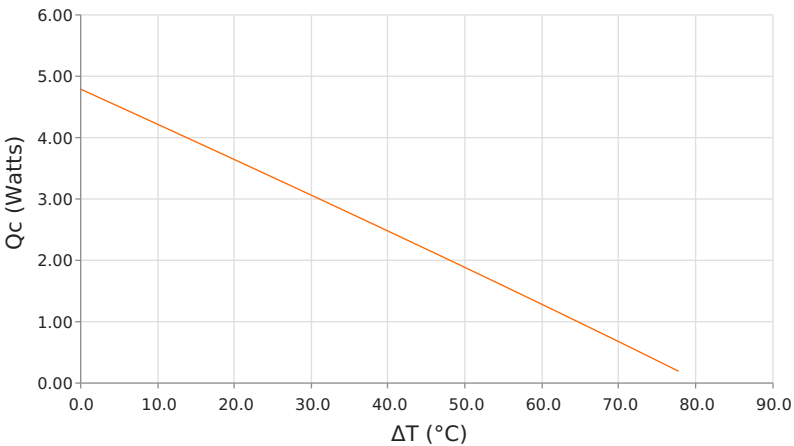
Total Heat Dissipated at Hot Side ($Q_h=Q_c+P_{in}$)
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



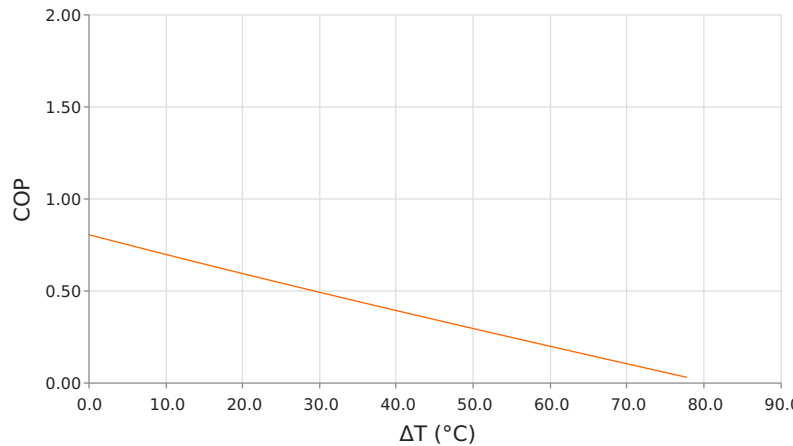
Total Heat Dissipated at Hot Side ($Q_h=Q_c+P_{in}$)
 $T_{hot} = 27\text{ }^{\circ}\text{C}$



Heat Pumped at Cold Side (Q_c)
 $T_{hot} = 50\text{ }^{\circ}\text{C}$ | operating = 1.6 Amps



Coefficient of Performance (COP = Q_c/P_{in})
 $T_{hot} = 50\text{ }^{\circ}\text{C}$ | operating = 1.6 Amps



Specifications

Hot Side Temperature	27.0 °C	50.0 °C	80.0 °C
Qcmax (ΔT = 0)	4.7 Watts	5.1 Watts	5.4 Watts
ΔTmax (Qc = 0)	72.9°C	81.8°C	92.1°C
Imax (I @ ΔTmax)	1.9 Amps	1.9 Amps	1.8 Amps
Vmax (V @ ΔTmax)	4.1 Volts	4.5 Volts	5.1 Volts
Module Resistance	1.97 Ohms	2.21 Ohms	2.53 Ohms
Max Operating Temperature	120 °C		
Weight	1.0 gram(s)		

Finishing Options

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
21	1.981 ±0.127 mm 0.078 ± 0.0050 in	N/A / N/A	Pre-tinned	Lapped	50.8 mm 2.00 in

Sealing Options

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

Notes

Max operating temperature: 120°C
Do not exceed Imax or Vmax when operating module
Reference assembly guidelines for recommended installation
Solder tinning also available on metallized ceramics

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